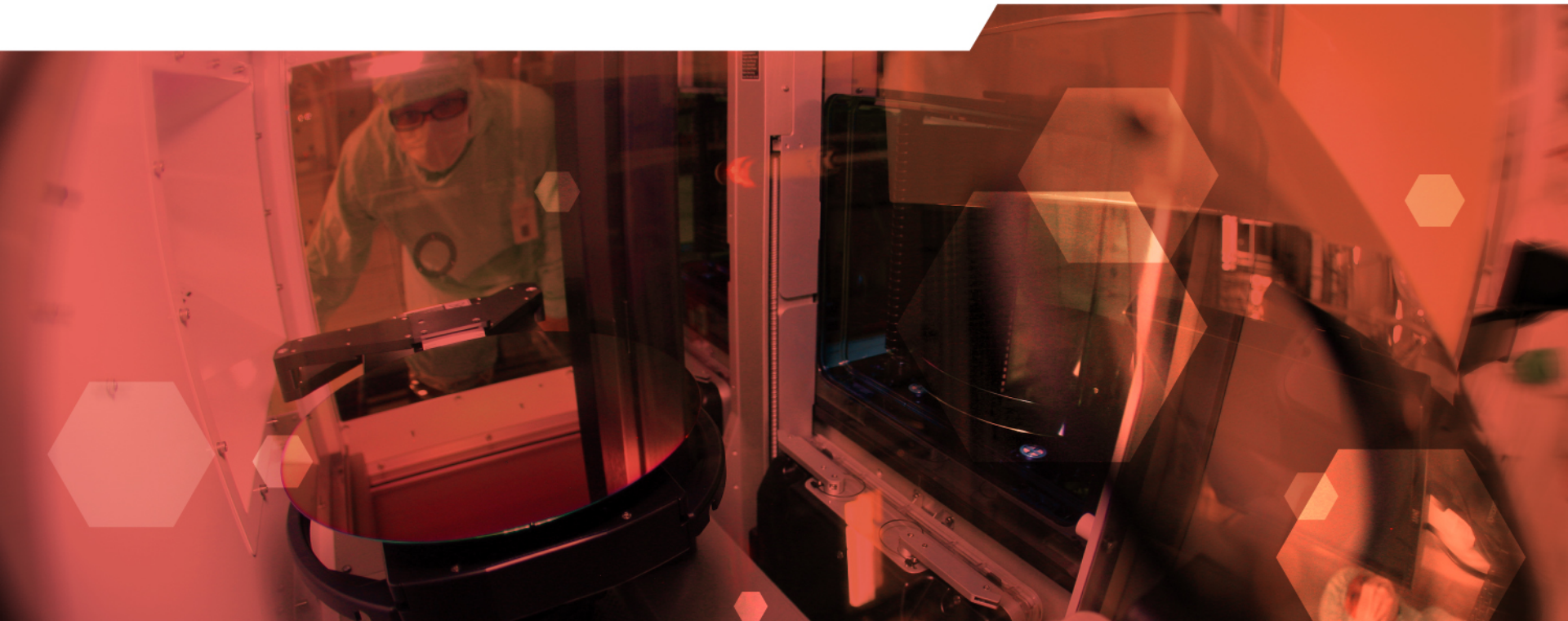


Japan TC Chapter 3D Packaging & Integration Global Technical Committee

Liaison Report

March 2019

V1.0



Outline

- Meeting Information
- Announcement
- Leadership / Leadership Changes
- Committee Structure Changes
- Organization Chart
- Ballot Results
- Activities Approved via GCS
- Authorized Activities / Other Activities
- Authorized Ballots
- Abolished SNARFs
- Inactive Status
- Task Force Highlights
- Open SNARFs
- Requests
- Five-Year Review
- Staff Contact

Optional

Meeting Information

- Last meeting
 - February 22, 2019 at the Japan Winter 2019 Meetings
 - SEMI Japan office, Tokyo
- Next meeting
 - June 7, 2019 at the Japan Summer 2019 Meetings
 - SEMI Japan office, Tokyo

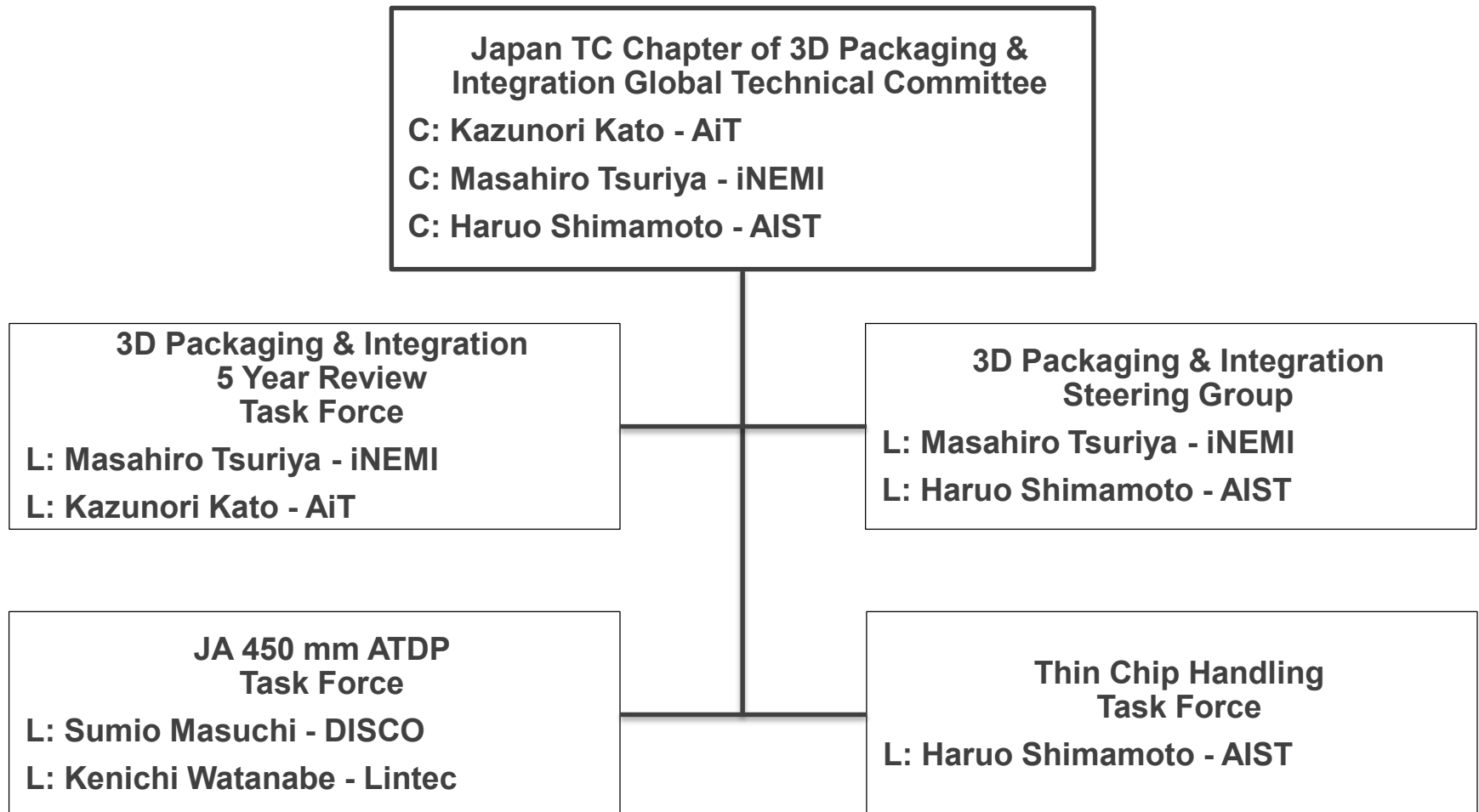
<http://www1.semi.org/en/standards-events>

Leadership

Co-chairs

- Kazunori Kato – AiT
 - 1st GCS voting member
 - 1st 3D Packaging & Integration representative to the JRSC
- Masahiro Tsuruya – iNEMI
 - 2nd GCS voting member
 - 3rd 3D Packaging & Integration representative to the JRSC
- Haruo Shimamoto – AIST
 - 2nd 3D Packaging & Integration representative to the JRSC

Organization Chart



Authorized Activities

Doc #	Type	SC/TF/CFG	Document Title/Details
6496	SNARF	3D Packaging & Integration 5 Year Review TF	Line Item Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength" - New SNARF approved at TC Chapter meeting held on 2/22/2019
6497	SNARF	JA 450 mm Assembly and Test Die Preparation TF	Line Item Revision to SEMI G95-0314: "Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process" with non-conforming title change to "Specification for Mechanical Features of 450 mm Load Port for Tape Frame Cassettes in the Backend Process" - New SNARF approved at TC Chapter meeting held on 2/22/2019
6498	SNARF	--	Reapproval of SEMI G96-1014 "Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending" - New SNARF approved at TC Chapter meeting held on 2/22/2019

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:
<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Authorized Ballots

Doc #	When	TF	Document Title/Details
6497	Cycle 3-2019	JA 450 mm Assembly and Test Die Preparation TF	Line Item Revision to SEMI G95-0314: “Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process” with non-conforming title change to “Specification for Mechanical Features of 450 mm Load Port for Tape Frame Cassettes in the Backend Process” – Authorized for ballot in voting Cycle 3-2019 at TC Chapter meeting on 2/22/2019
6498	Cycle 3-2019	--	Reapproval of SEMI G96-1014 “Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending” – Authorized for ballot in voting Cycle 3-2019 at TC Chapter meeting on 2/22/2019

Task Force Highlights

- Thin Chip Handling Task Force
 - #6424: New Standard: Test method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling
 - Ballot reviewed and passed with editorial change at the TC Chapter meeting on October 15 and also passed A&R in December 2018
 - Waiting for proof
- 3D Packaging & Integration 5 Year Review Task Force
 - #6423: Revision to SEMI G83-0912 “Specification for Bar Code Marking of Product Packages” and Withdrawal of SEMI G83.1-0912 “Specification for Bar Code Marking of Product Packages”
 - Ballot reviewed and passed as balloted at the TC Chapter meeting on October 15 and also passed A&R in December 2018
 - Waiting for proof

Report

- The TC Chapter exposed its activity at SEMICON Japan 2018 as follows.
 - Exhibition at "SEMI Standards" Booth
 - FO-PLP used materials such as PLP FOUP and PLP panels were exhibited in the booth. SEMI related documents and PLP technical documents are displayed in the booth.
 - Workshop at TechSPOT
 - Focus on FO-PLP
 - “What Industry STD are needed to be accepted by the users?”
 - Panelist: TOWA / Fujifilm / Panasonic
 - More than 30 attended



Thank you
Chie Yanagisawa
cyanagiswa@semi.org

Backup

<Region> TC Chapter
<Committee Name>
Global Technical Committee

SEMI Corporate Color Palette



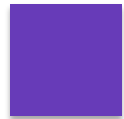
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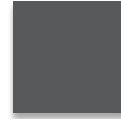
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R = 128
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B = 133



R = 167
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B = 172

Stay
within
standard
color
palette